

Abstract

A high impedance surface and a method of making same. The surface includes a molded structure
5 having a repeating pattern of holes therein and a repeating pattern of sidewall surfaces, the holes
penetrating the structure between first and second major surfaces thereof and the sidewall
surfaces joining the first major surface. A metal layer is put on said molded structure, the metal
layer being in the holes, covering at least a portion of the second major surface, covering the
sidewalls and portions of the first major surface to interconnect the sidewalls with other
10 sidewalls via the metal layer on the second major surface and in the holes.